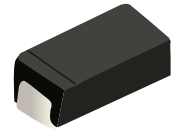


FEATURES

- | Glass Passivated Die Construction
- | Fast Recovery Time for High Efficiency
- | Low reverse leakage
- | Ideally Suited for Automatic Assembly



DO-214AC(SMA)



Schematic Symbol

MECHANICAL DATA

- | Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- | Moisture Sensitivity: Level 1 per J-STD-020

APPROVALS

RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003

MAXIMUM RATINGS AND CHARACTERISTICS (T_A=25°C)

Parameter	Symbol	ES1A	ES1B	ES1C	ES1D	ES1F	ES1G	ES1H	ES1J	Unit
Marking		ES1A	ES1B	ES1C	ES1D	ES1F	ES1G	ES1H	ES1J	
Maximum repetitive peak reverse voltage	V _{RRM}	50	100	150	200	300	400	500	600	V
Maximum RMS voltage	V _{RMS}	35	70	105	140	210	280	350	420	
Maximum DC blocking voltage	V _{DC}	50	100	150	200	300	400	500	600	
Maximum average forward rectified current at T _L =100°C	I _{F(AV)}	1.0								A
Surge peak forward current,8.3ms single half sine-wave superimposed on rated load per diode	I _{FSM}	30.0								
Maximum instantaneous forward voltage at 1.0A	V _F	0.95			1.30		1.7			V
Maximum DC reverse current T _A =25°C at rated DC blocking voltage	I _R	5.0								uA
		500								
Maximum reverse recovery time(Note 1)	T _{rr}	35								ns
Typical junction capacitance (Note2)	C _J	18.0								pF
Typical thermal resistance	R _{θJA}	80.0								°C/W
Operating junction and storage temperature range	T _J ,T _{STG}	-55 to +150								°C

Note :

- 1.Reverse recovery time test condition: I_F=0.5A I_R=1.0A I_{rr}=0.25A
- 2.Measured at 1MHz and applied reverse voltage of 4.0V D.C.

CHARACTERISTIC CURVES

Fig. 1- Derating Curve Output Rectified Current

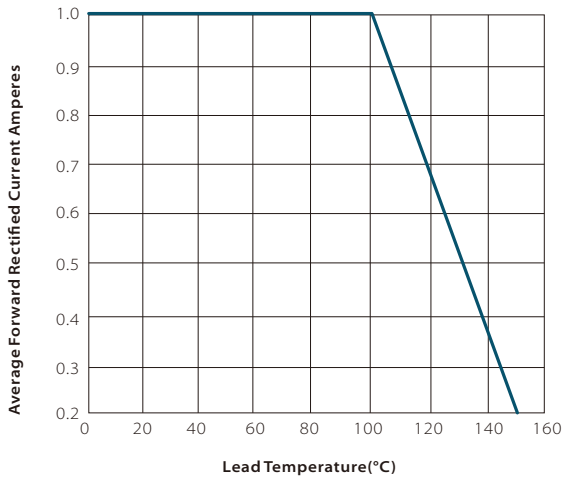


Fig. 2-maximum Non-repetitive Peak Forward Surge Current Perleg

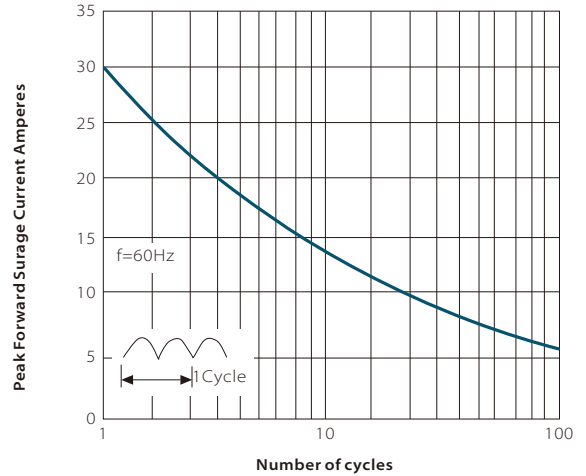


Fig. 3-Typical Forward Voltage Characteristics

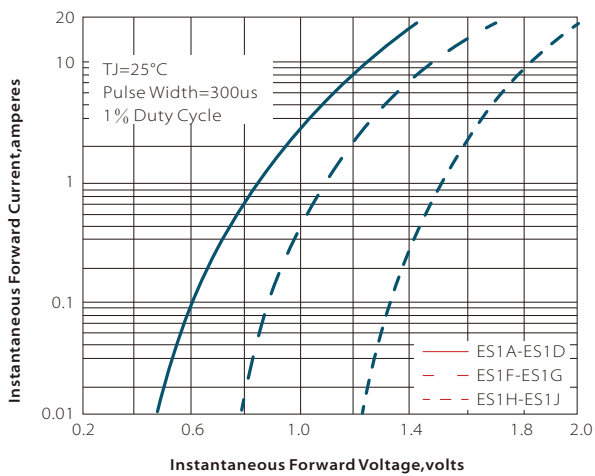
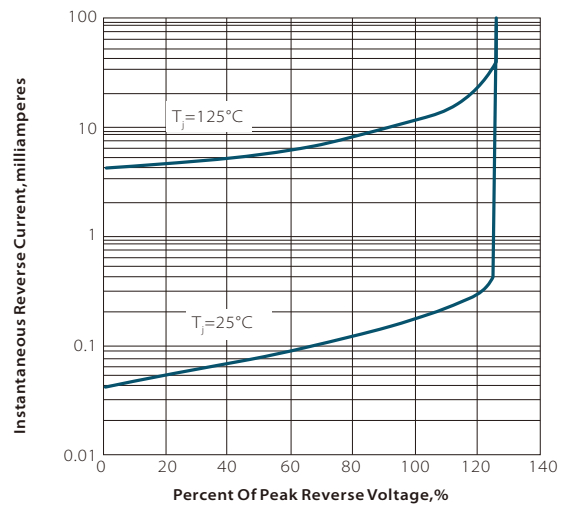
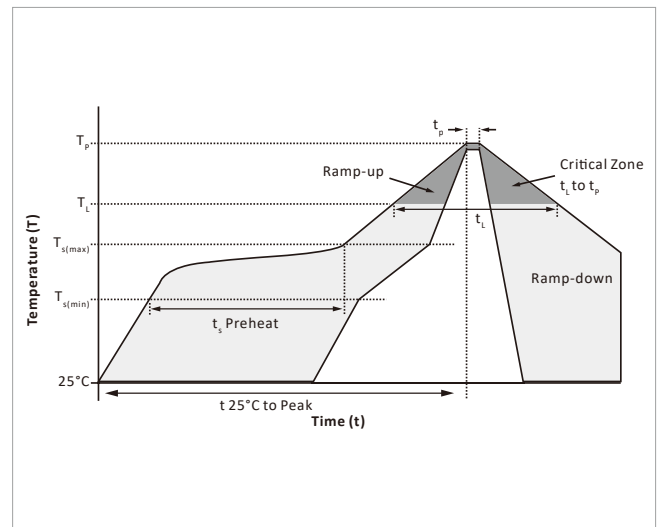


Fig. 4-Typical Reverse Leakage Characteristics

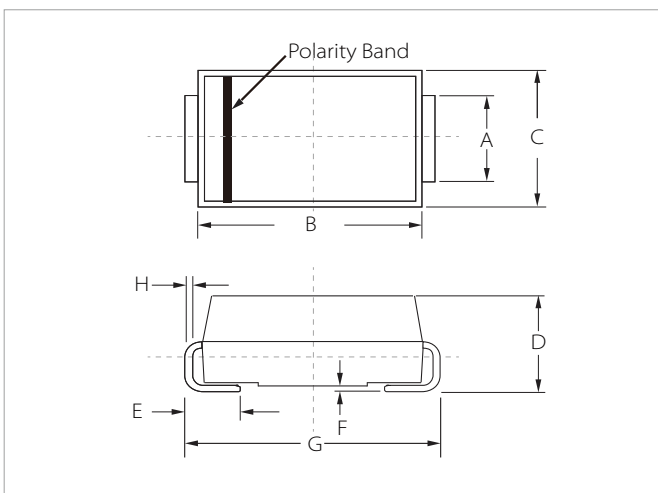


SOLDERING PARAMETERS

Reflow Condition		Lead-free assembly
Pre Heat	Temperature Max ($T_{s(min)}$)	150°C
	Temperature Max ($T_{s(max)}$)	200°C
	Time (min to max) (t_p)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak)		3°C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/second max
Reflow	Temperature (T_L) (Liquidus)	217°C
	Time (min to max) (t_L)	60 – 150 seconds
Peak Temperature (T_p)		260°C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes max.
Do not exceed		260°C

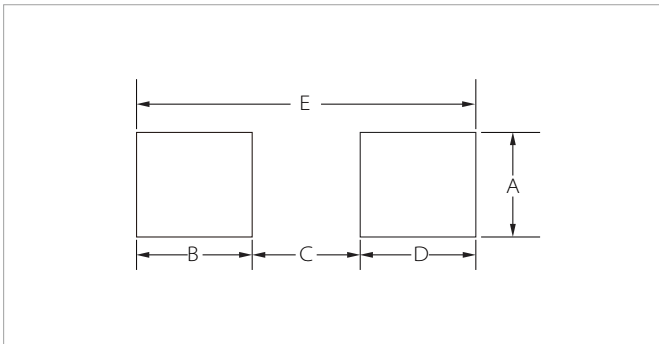


DO-214AC(SMA) PACKAGE INFORMATION



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	1.20	1.60	0.047	0.063
B	4.20	4.60	0.165	0.181
C	2.60	2.80	0.102	0.110
D	2.10	2.40	0.083	0.094
E	0.76	1.52	0.030	0.060
F	0.02	0.20	0.001	0.008
G	4.85	5.25	0.191	0.207
H	0.15	0.30	0.006	0.012

RECOMMENDED PAD LAYOUT DIMENSIONS



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	1.63	-	0.064	-
B	1.45	-	0.057	-
C	-	2.80	-	0.090
D	1.45	-	0.057	-
E	5.28REF		0.208REF	

ORDERING INFORMATION

Part Number	Component Package	QTY/Reel	Reel Size
ES1A-ES1J	DO-214AC(SMA)	5000PCS	13"

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